

Title of Change:	Power Schottky substrate R34A05T epi window change
Effective date:	23 Jun 2025
Contact information:	Contact your local onsemi Sales Office
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi, ISMF Malaysia	None

Description and Purpose:

This PB is to announce that onsemi will do optimization for substrate epi window.

Substrate	Before change	After change
R34A05T	Thickness (um): 10.4 - 11.6, Res (ohmcm): 2 - 2.4	Thickness (um): 10.7 - 11.6, Res (ohmcm): 1.9 - 2.25

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

MBRA1H100T3G	MBRM2H100T3G	MBRM1H100T3G
MBR2H100SFT3G	MBR1H100SFT3G	

Appendix A: Changed Products

PCN#: PB26418X
Issue Date: May 27, 2025

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MBRM2H100T3G		MBR2H100SFT3G		
MBR2H100SFT3G		MBR2H100SFT3G		
MBRA1H100T3G		MBR2H100SFT3G		
MBRM1H100T3G		MBR2H100SFT3G		
MBR1H100SFT3G		MBR2H100SFT3G		